



#5 2121
8-1-01

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Akram et al.

Serial No.: 09/653,272

Filed: August 31, 2000

For: METHOD FOR USING DATA
REGARDING MANUFACTURING
PROCEDURES INTEGRATED CIRCUITS
(IC'S) HAVE UNDERGONE, SUCH AS
REPAIRS, TO SELECT PROCEDURES THE
IC'S WILL UNDERGO, SUCH AS
ADDITIONAL REPAIRS

Examiner: Unknown

Group Art Unit: 2121

Attorney Docket No.: 4181US (96-973.2)

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CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail (under 37 C.F.R. § 1.8(a)) on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, Washington, D.C. 20231.

July 23, 2001
Date of Deposit

Signature of registered practitioner or other person
having reasonable basis to expect mailing to occur on
date of deposit shown pursuant to 37 C.F.R. §
1.8(a)(1)(ii)

Deidra Pfeil
Typed/printed name of person whose signature is
contained above

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

In compliance with the duty to disclose information material to patentability pursuant to 37 C.F.R. § 1.56, it is respectfully requested that this Supplemental Information Disclosure Statement be entered and the documents listed on attached Form PTO-1449 be considered by the Examiner and made of record. The listed documents are from a related application Serial No. 09/292,655, filed April 14, 1999. Copies of the listed documents are enclosed pursuant to 37 C.F.R. § 1.98(a).

In accordance with 37 C.F.R. § 1.97(g) and (h), filing of this Supplemental Information Disclosure Statement is not to be construed as a representation that a search has been made or an admission that the information cited herein is, or is considered to be, material to patentability as



Serial No. 09/653,272

defined in 37 C.F.R. § 1.56(b). Further, no representation is made by Applicants herein that no other possible material information as defined in 37 C.F.R. § 1.56 (b) exists.

DOCUMENTS

U.S. Patent Documents

<u>U.S. Patent No.</u>	<u>Issue Date</u>	<u>Inventor</u>
4,510,673	04/1985	Shils et al.
5,253,208	10/1993	Kang
5,907,492	05/1999	Akram et al.
5,927,512	07/1999	Beffa
6,122,563	09/2000	Beffa

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Applicants offer to supply any explanation or discussion of the documents which the Examiner feels is necessary or desirable and which is requested.

This Supplemental Information Disclosure Statement is filed after the mailing date of the first Office Action on the merits. I hereby certify that no item of information contained in the Supplemental Information Disclosure Statement was cited in a communication from a foreign patent office in a counterpart foreign application or, to the knowledge of the undersigned after making reasonable inquiry, was known to any individual designated in 37 C.F.R. § 1.56(c) more than three months prior to the filing of the statement.

Respectfully submitted,

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Date: July 23, 2001

JRD/sls:djp

Enclosures: Form PTO-1449
Copy of documents cited